

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2821	semiconductor and ((substrate or wafer) with central with (hole or aperture or hollow or groove))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:52
S2	2821	semiconductor and ((substrate or wafer) with (central with (hole or aperture or hollow or groove)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:54
S3	10138	semiconductor and ((substrate or wafer) with (cylindrical))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:55
S4	743	semiconductor and ((substrate or wafer) with (cylindrical with opening))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:00
S5	229	S4 and cooling	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:55
S6	22	S5 and (opening with axis)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 13:56
S7	171	semiconductor with (substrate or wafer) with cylindrical with opening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:02
S8	33	semiconductor with (substrate or wafer) with (cylindrical adj (opening or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:07
S9	1	S8 and cooling	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:08
S10	553	257/618.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/27 14:08